

ON Semiconductor			10/15/2019	
Base Part		FDMA1032CZ	HF	Pb-free
Orderable Part		FDMA1032CZ	Total weight (mg)	9.879
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.569	Silicon (Si)	7440-21-3	100
Die Attach Epoxy	0.108	Silver (Ag)	7440-22-4	85
		Phenolic Resin-2	54208-63-8	15
Lead Frame	4.24	Zinc (Zn)	7440-66-6	0.14150943
		Iron (Fe)	7439-89-6	2.40566038
		Copper (Cu)	7440-50-8	97.40566038
		Phosphorus (P)	7723-14-0	0.04716981
Mold Compound-Black	4.878	Ortho Cresol Novolac Resin	29690-82-2	10.00410004
		Carbon Black (C)	1333-86-4	1.00451005
		Fused Silica (SiO2)	60676-86-0	88.99138991
Plating	0.049	Palladium (Pd)	7440-05-3	8.16326531
		Nickel (Ni)	7440-02-0	89.79591837
		Gold (Au)	7440-57-5	2.04081633
Wire Bond - Cu	0.035	Copper (Cu)	7440-50-8	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels for dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				